

This document is the property of Amphenol Corporation and is delivered on the express condition that is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.

The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.



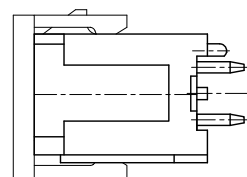
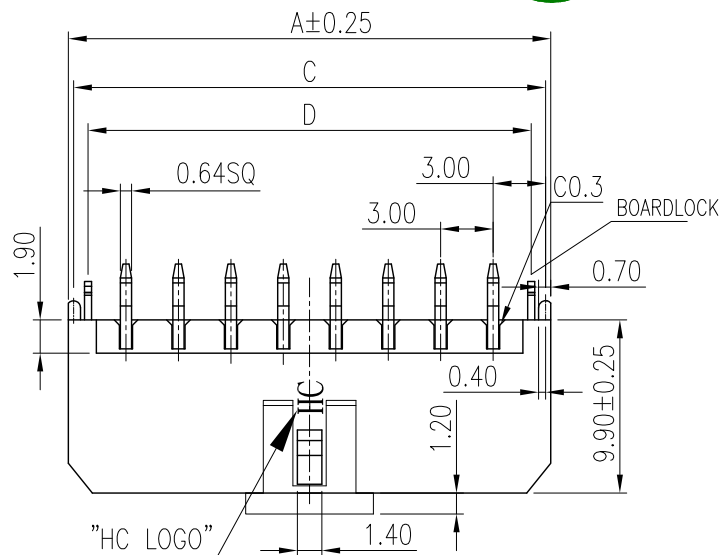
ORIGINAL

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-17175	RELEASE TO PRODUCTION	07/11/2017	Roger Tsai
B	NE-17213	ADD MORE DIFFERENT SECTION(WITHOUT CAP) FOR THE T&R PACKAGE	08/07/2017	Roger Tsai
C	NE-18163	UPDATE PACKING DRAWING	08/07/2018	Roger Tsai

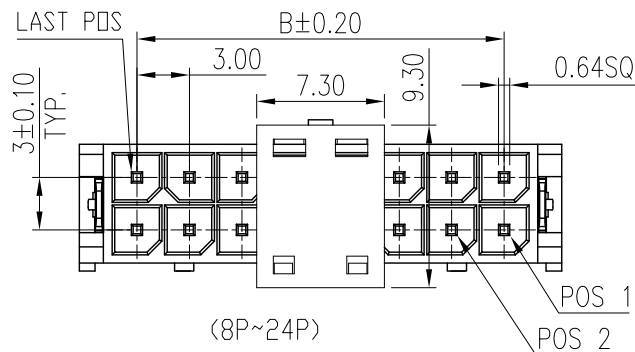


NOTE:

- MATERIAL  
INSULATOR: HIGH TEMP. THERMOPLASTIC, OPTIONS, UL 94V-0, COLOR OPTIONS  
CONTACT MATERIAL: HIGH PERFORMANCE COPPER ALLOY.  
BOARDLOCK: COPPER ALLOY.
- FINISH:  
CONTACT: SELECTIVE PLATING. ;  
SOLDERING AREA: MATTE TIN 100u" MIN. OR GOLD PLATING;  
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.  
BOARDLOCK:  
MATTE TIN 100u" MIN. PLATING;  
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
- THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
- PACKING MUST BE PER Amphenol PACKING SPECIFICATION
- TO ENSURE CURRENT RATING CAPABILITY, AMPHENOL HIGH CURRENT PART NUMBERS IN THE CHART ARE RECOMMENDED.  
(G88MPH CABLE HOUSING SERIES WITH G88MPC CABLE TERMINAL SERIES)
- PRODUCT SPECIFICATION REFER TO : PS-7528.
- TEST SUMMARY REFER TO : TS-7528-001.



(W/O BOARDLOCK)



(8P~24P)

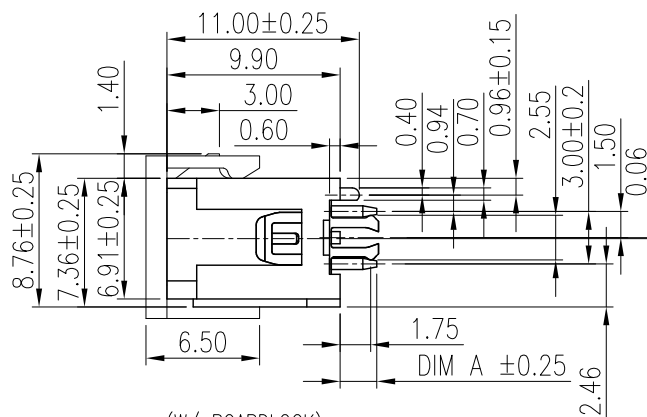
PART NO. G88MPXX1X2XXREU

No. OF CIRCUIT

CONTACT FINISH  
0: 100u" MATTE TIN  
1: FULL GOLD FLASH  
2: 15 u" GOLD  
3: 30 u" GOLD

BOARD MOUNT / CAP  
C: WITH BOARDLOCK / WITH CAP  
D: WITHOUT BOARDLOCK / WITH CAP  
1: WITH BOARDLOCK / WITHOUT CAP  
2: WITHOUT BOARDLOCK / WITHOUT CAP

INSULATOR  
0: LCP (BLACK) ,DIM A=2.10  
1: LCP (NATURAL) ,DIM A=2.10  
2: LCP (NATURAL) ,DIM A=2.60  
7: LCP (NATURAL) ,DIM A=3.20  
8: LCP (BLACK) ,DIM A=3.20  
9: LCP (BLACK) ,DIM A=2.60



(W/ BOARDLOCK)

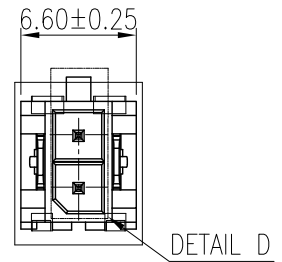
POS	A	B	C	D
02	6.60		6.00	4.3
04	9.60	3.00	9.00	7.3
06	12.60	6.00	12.00	10.3
08	15.60	9.00	15.00	13.3
10	18.60	12.00	18.00	16.3
12	21.60	15.00	21.00	19.3
14	24.60	18.00	24.00	22.3
16	27.60	21.00	27.00	25.3
18	30.60	24.00	30.00	28.3
20	33.60	27.00	33.00	31.3
22	36.60	30.00	36.00	34.3
24	39.60	33.00	39.00	37.3

TOLERANCE	APPROVALS	DATE	TITLE	UNIT	SIZE	PART No.
X. ±0.30	DRAWN Debby Hung	08/07/2018	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK (T&R PACKING)	mm	A3	G88MPXX1X2XXREU
X.X ±0.20	CHECKED Sandy Wu	08/07/2018		SCALE NA	SHEET 1 OF 4	
X.XX ±0.10	APPROVED Roger Tsai	08/07/2018		PROJECT CODE PHD	DWG No. G88MPXX1X2XXREU	REV. C
ANGULAR ±1°	DWG TYPE CUST DWG					
UNLESS OTHERWISE SPECIFIED						

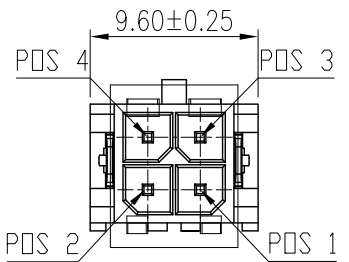
ORIGINAL

This document is the property of Amphenol Corporation and is delivered on the express condition that is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.  
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

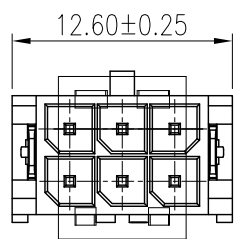
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-17175	RELEASE TO PRODUCTION	07/11/2017	Roger Tsai
B	NE-17213	ADD MORE DIFFERENT SECTION(WITHOUT CAP) FOR THE T&R PACKAGE	08/07/2017	Roger Tsai
C	NE-18163	UPDATE PACKING DRAWING	08/07/2018	Roger Tsai



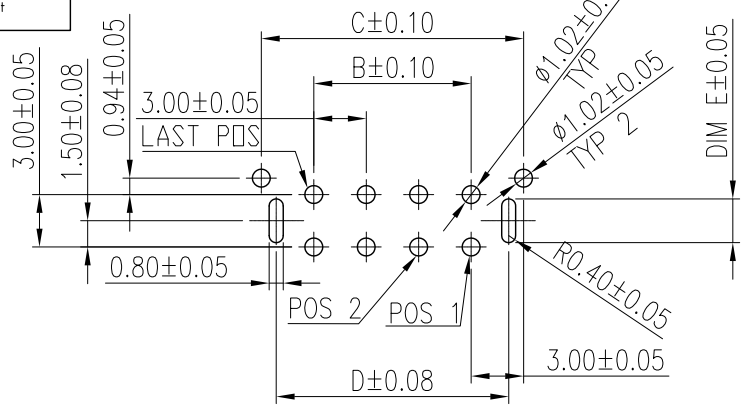
(2X1POS)



(2X2POS)

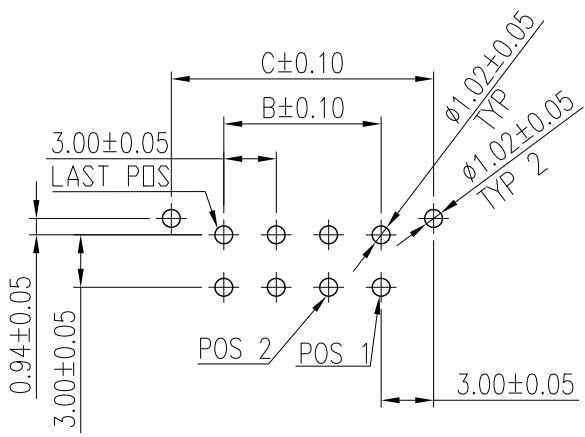


(2X3POS)

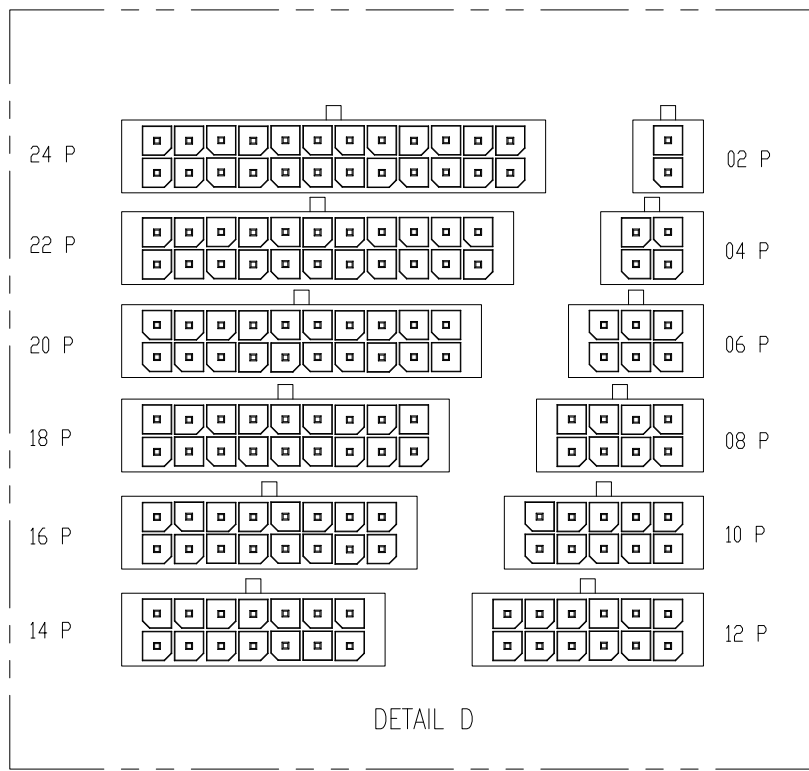


DIM E: 2.50 FOR NON-ZERO INSERTION FORCE  
DIM E: 3.00 FOR ZERO INSERTION FORCE

02~24P (W/BOARDLOCK)  
RECOMMENDED PCB LAYOUT (T=1.60mm)



02~24P (W/O BOARDLOCK)  
RECOMMENDED PCB LAYOUT (T=1.60mm)



TOLERANCE		APPROVALS		DATE	TITLE		Amphenol <sup>®</sup>									
X.		DRAWN	Debby Hung	08/07/2018	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK (T&R PACKING)		Amphenol Corporation Amphenol Taiwan Corporation									
X.X	±0.30	CHECKED	Sandy Wu	08/07/2018												
X.XX	±0.20	APPROVED	Roger Tsai	08/07/2018												
X.XXX	±0.10	ANGULAR		±1°	UNLESS OTHERWISE SPECIFIED		DWG TYPE	CUST DWG	PROJECT CODE	PHD	UNIT	mm	SIZE	A3	PART No.	G88MPXX1X2XXREU
							DWG No.	G88MPXX1X2XXREU	REV.	C	SCALE	NA	SHEET	2 OF 4		

This document is the property of Amphenol Corporation and is delivered on the express condition that is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.

The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

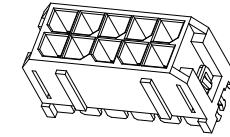


ORIGINAL

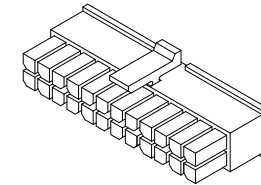


REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-17175	RELEASE TO PRODUCTION	07/11/2017	Roger Tsai
B	NE-17213	ADD MORE DIFFERENT SECTION(WITHOUT CAP) FOR THE T&R PACKAGE	08/07/2017	Roger Tsai
C	NE-18163	UPDATE PACKING DRAWING	08/07/2018	Roger Tsai

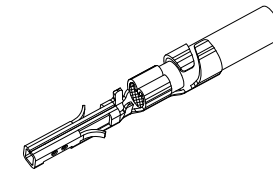
POS.	BOARD-MOUNT P/N	CABLE HOUSING P/N	CABLE TERMINAL P/N	AWG NO.	PLATING OPTIONS
02	G88MP021X2XXREU	G88MPH0222CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
04	G88MP041X2XXREU	G88MPH0422CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
06	G88MP061X2XXREU	G88MPH0622CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
08	G88MP081X2XXREU	G88MPH0822CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
10	G88MP101X2XXREU	G88MPH1022CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
12	G88MP121X2XXREU	G88MPH1222CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
14	G88MP141X2XXREU	G88MPH1422CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
16	G88MP161X2XXREU	G88MPH1622CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
18	G88MP181X2XXREU	G88MPH1822CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
20	G88MP201X2XXREU	G88MPH2022CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
22	G88MP221X2XXREU	G88MPH2222CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
24	G88MP241X2XXREU	G88MPH2422CEU	G88MPC0232XCEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPC0X32CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD



AMPHENOL BOARD-MOUNT



AMPHENOL CABLE HOUSING

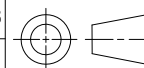


AMPHENOL CABLE TERMINAL

NOTE:  
TO ENSURE CURRENT RATING CAPABILITY, AMPHENOL HIGH CURRENT PART NUMBERS IN THE CHART ARE RECOMMENDED.

(G88MPH CABLE HOUSING SERIES WITH G88MPC CABLE TERMINAL SERIES)

TOLERANCE		APPROVALS		DATE	TITLE G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK (T&R PACKING)	Amphenol <sup>®</sup> Amphenol Corporation Amphenol Taiwan Corporation				
X.		DRAWN	Debby Hung	08/07/2018		UNIT mm SCALE NA	SIZE A3 SHEET 3 OF 4	PART No. G88MPXX1X2XXREU		
X.X	±0.30	CHECKED	Sandy Wu	08/07/2018				DWG No. G88MPXX1X2XXREU		
X.XX	±0.20	APPROVED	Roger Tsai	08/07/2018		REV. C				
X.XXX	±0.10	UNLESS OTHERWISE SPECIFIED		DWG TYPE CUST DWG	PROJECT CODE PHD					



This document is the property of Amphenol Corporation and is delivered on the express condition that is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.

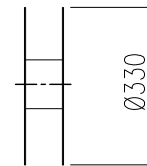
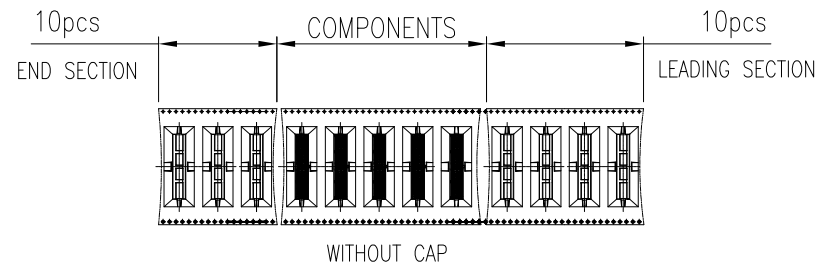
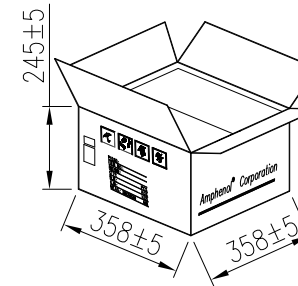
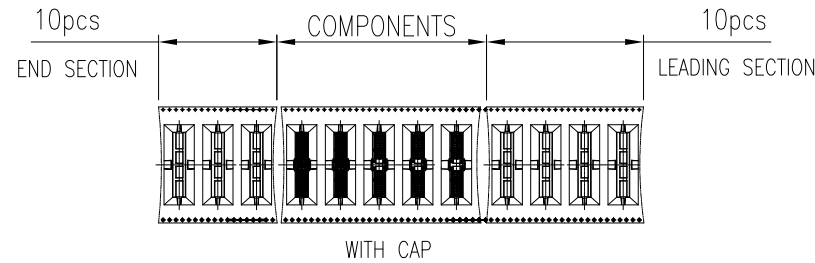
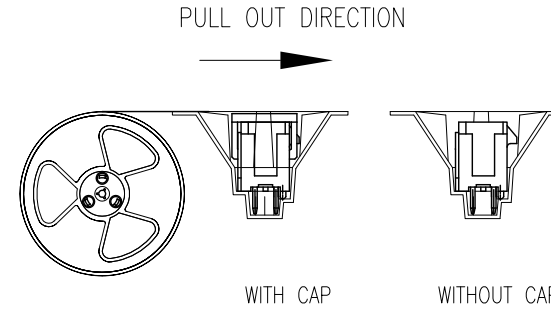
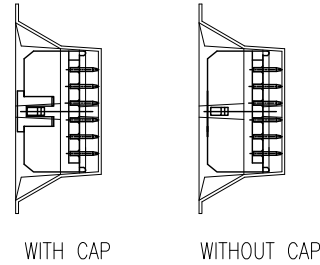
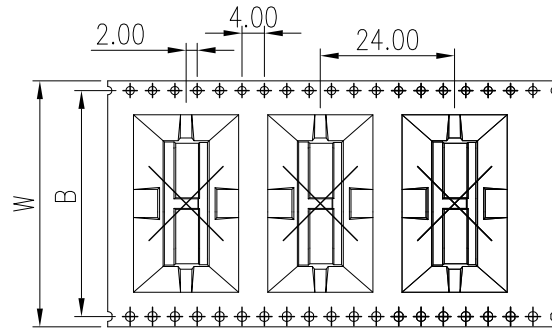
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.



ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-17175	RELEASE TO PRODUCTION	07/11/2017	Roger Tsai
B	NE-17213	ADD MORE DIFFERENT SECTION(WITHOUT CAP) FOR THE T&R PACKAGE	08/07/2017	Roger Tsai
C	NE-18163	UPDATE PACKING DRAWING	08/07/2018	Roger Tsai



POS	W(mm)	B(mm)	PCS/REEL	PCS/CARTON
2	32	28.4	150	900
4				
6				
8	44	40.4	150	600
10				
12				
14				
16				
18	72	68.4	150	450
20				
22				
24				

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol <sup>®</sup>						
X.		DRAWN	Debby Hung	08/07/2018	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK (T&R PACKING)		Amphenol Corporation Amphenol Taiwan Corporation						
X.X	±0.30	CHECKED	Sandy Wu	08/07/2018									
X.XX	±0.20	APPROVED	Roger Tsai	08/07/2018									
X.XXX	±0.10						UNIT	mm	SIZE	A3	PART No.	G88MPXX1X2XXREU	
ANGULAR	±1°						SCALE	NA	SHEET	4 OF 4	DWG No.	G88MPXX1X2XXREU	
UNLESS OTHERWISE SPECIFIED		DWG TYPE		CUST DWG	PROJECT CODE		PHD				REV.		C